

38825

U.S. UTILITY Patent Application

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PATENT NUMBER and
ISSUE DATE

APPL NUM 10016008	FILING DATE 12/11/2001	CLASS 439 428	SUBCLASS 689	GAU 763 1772	EXAMINER DEO
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**APPLICANTS: Ushiki Takehito; Tsunoda Hitoshi;

**CONTINUING DATA VERIFIED:
THIS APPLICATION IS A DIV OF 09/346,004 07/01/1999
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hardened 4/16/02

** FOREIGN APPLICATIONS VERIFIED:
JAPAN 10-208633 07/08/1993
g r

PG-PUB <input checked="" type="checkbox"/>	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>	ATTORNEY DOCKET NO
Foreign priority claimed 35 USC 119 conditions met Verified and Acknowledged Examiners's initials		<input checked="" type="checkbox"/> yes <input type="checkbox"/> no <input checked="" type="checkbox"/> yes <input type="checkbox"/> no g r	
TITLE : Semiconductor wafer, method for producing the same, and wafer chuck			

U.S. DEPT. OF COMM /PAT. & TM-PTO-436L (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
Assistant Examiner		Total Claims	Print Claim for O.G.
Primary Examiner		DRAWING	
PREPARED FOR ISSUE		Sheets Drawg.	Figs. Drawg.
Application Examiner		Print Fig.	
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